

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

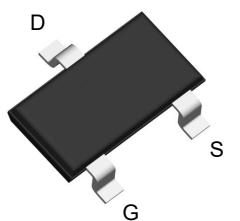
Product Summary



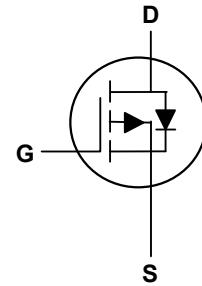
V_{DS}	-20	V
I_D	-6	A
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	25	mΩ
$R_{DS(ON)}$ (at $V_{GS}=-2.5V$)	30	mΩ

Applications

- High Frequency Point-of-Load,Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch



SOT23-3L Top View



Absolute Maximum Ratings($T_A=25^\circ C$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	-6	A
Pulsed Drain Current	I_{DM}	-24	A
Total Power Dissipation	P_D	1.2	W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	---	100	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}$, $I_D=-250\mu\text{A}$	-20	---	---	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=-4.5\text{V}$, $I_D=-6\text{A}$	---	20	25	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$, $I_D=-5\text{A}$	---	25	30	$\text{m}\Omega$
		$V_{\text{GS}}=-1.8\text{V}$, $I_D=-3\text{A}$	---	38	45	$\text{m}\Omega$
		$V_{\text{GS}}=V_{\text{DS}}$, $I_D = -250\mu\text{A}$	-0.5	-0.7	-1.0	V
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}}=V_{\text{DS}}$, $I_D = -250\mu\text{A}$	-0.5	-0.7	-1.0	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 12\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
Forward Transconductance	g_{fs}	$V_{\text{DS}}=-5\text{V}$, $I_D=-6\text{A}$	---	5	---	S
Total Gate Charge	Q_g	$V_{\text{DS}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_D=-6\text{A}$	---	17	---	nC
Gate-Source Charge	Q_{gs}		---	4.1	---	
Gate-Drain Charge	Q_{gd}		---	4.3	---	
Turn-On Delay Time	$T_{\text{d(on)}}$	$V_{\text{DD}}=-10\text{V}$, $I_D=-2.8\text{A}$, $V_{\text{GS}}=-4.5\text{V}$, $R_G=6\Omega$, $R_L=10\Omega$	---	25	---	ns
Rise Time	T_r		---	30	---	
Turn-Off Delay Time	$T_{\text{d(off)}}$		---	70	---	
Fall Time	T_f		---	50	---	
Input Capacitance	C_{iss}	$V_{\text{DS}}=-10\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2100	---	pF
Output Capacitance	C_{oss}		---	498	---	
Reverse Transfer Capacitance	C_{rss}		---	300	---	

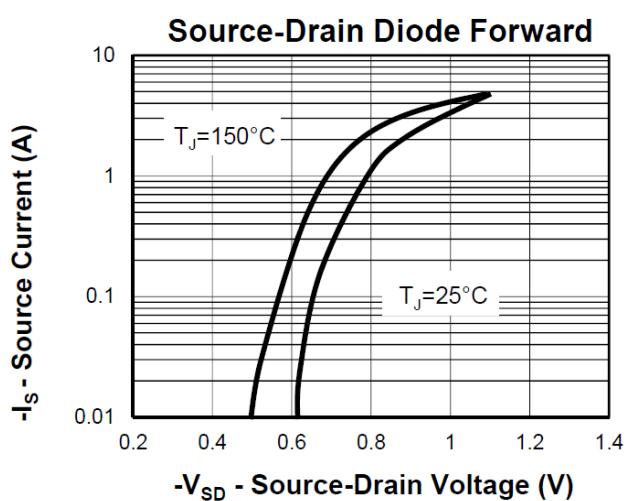
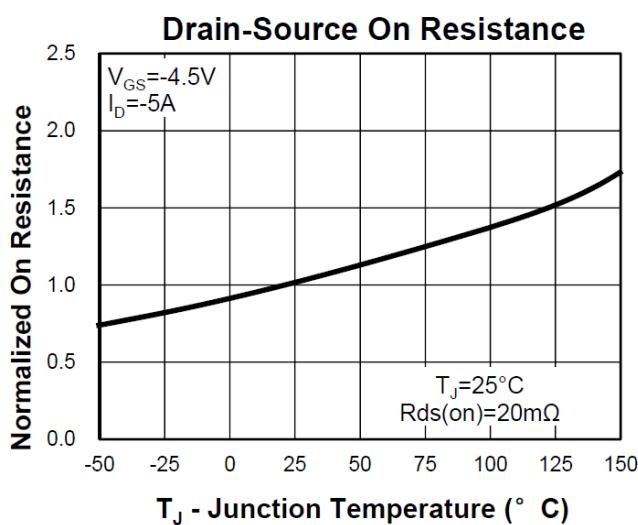
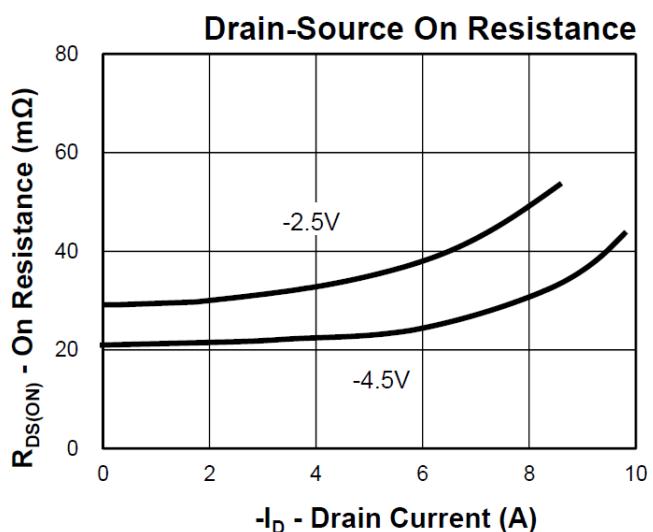
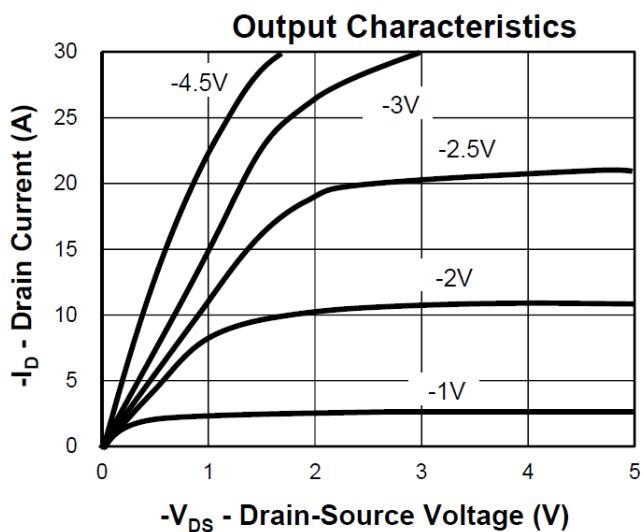
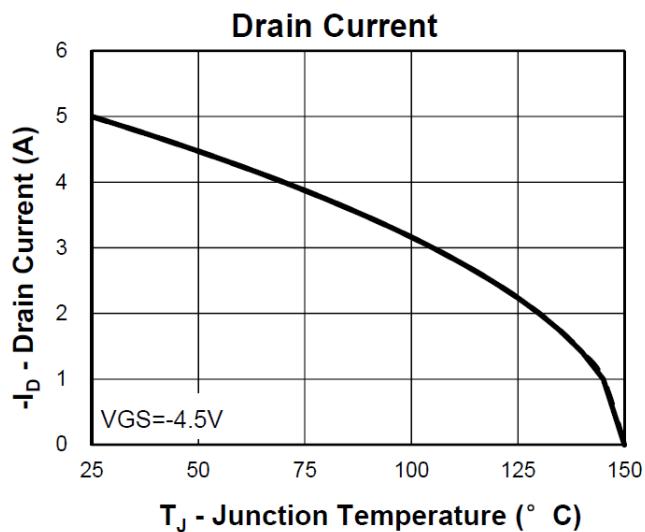
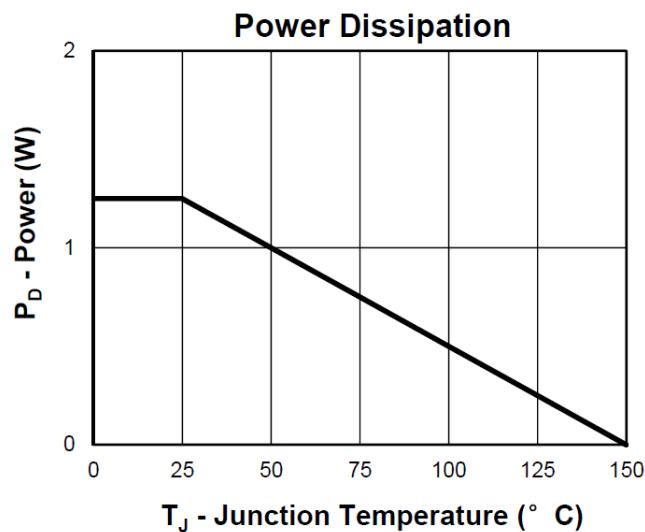
Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current ²	I_s		---	---	-6	A
Diode Forward Voltage ¹	V_{SD}	$V_{\text{GS}}=0\text{V}$, $I_s=-1.25\text{A}$, $T_J=25^\circ\text{C}$	---	-0.81	-1.2	V

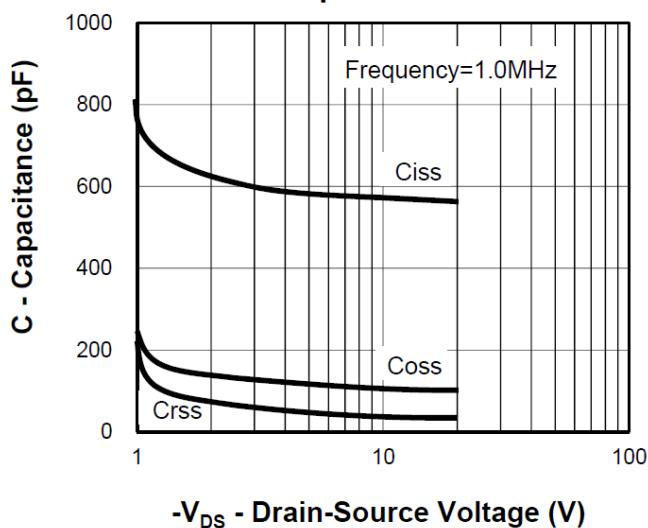
Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

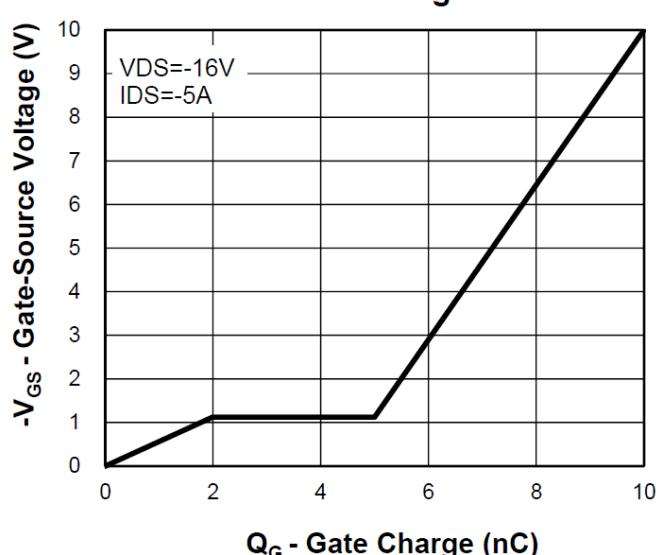
Typical Characteristics



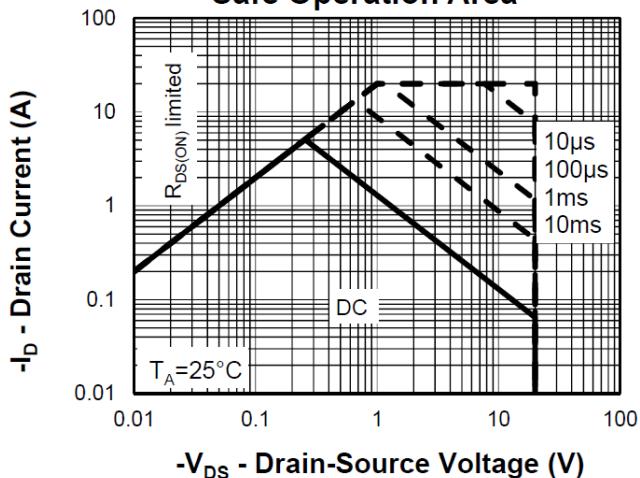
Capacitance



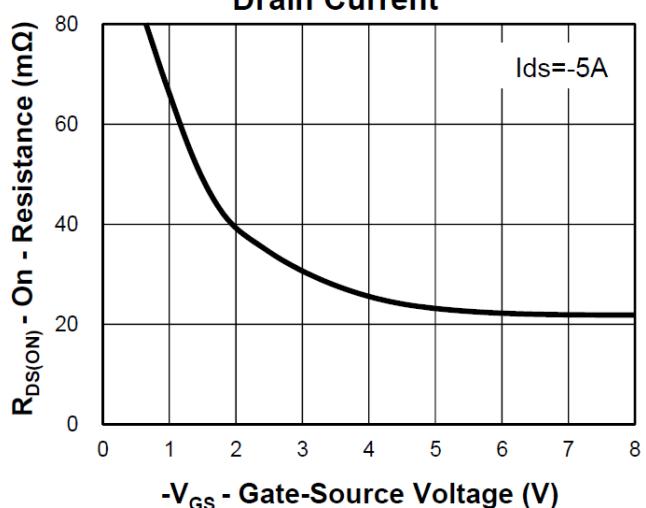
Gate Charge



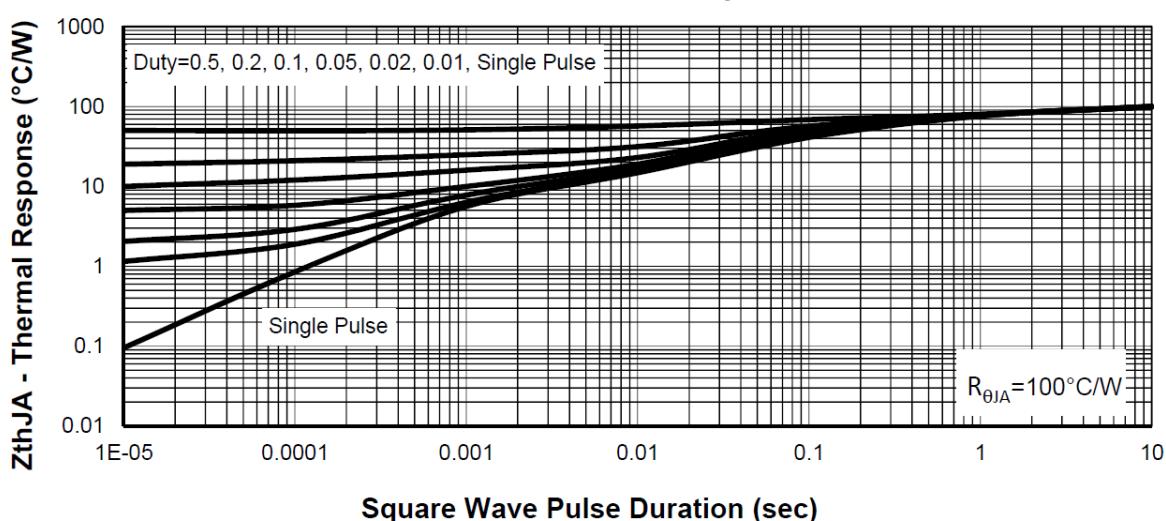
Safe Operation Area



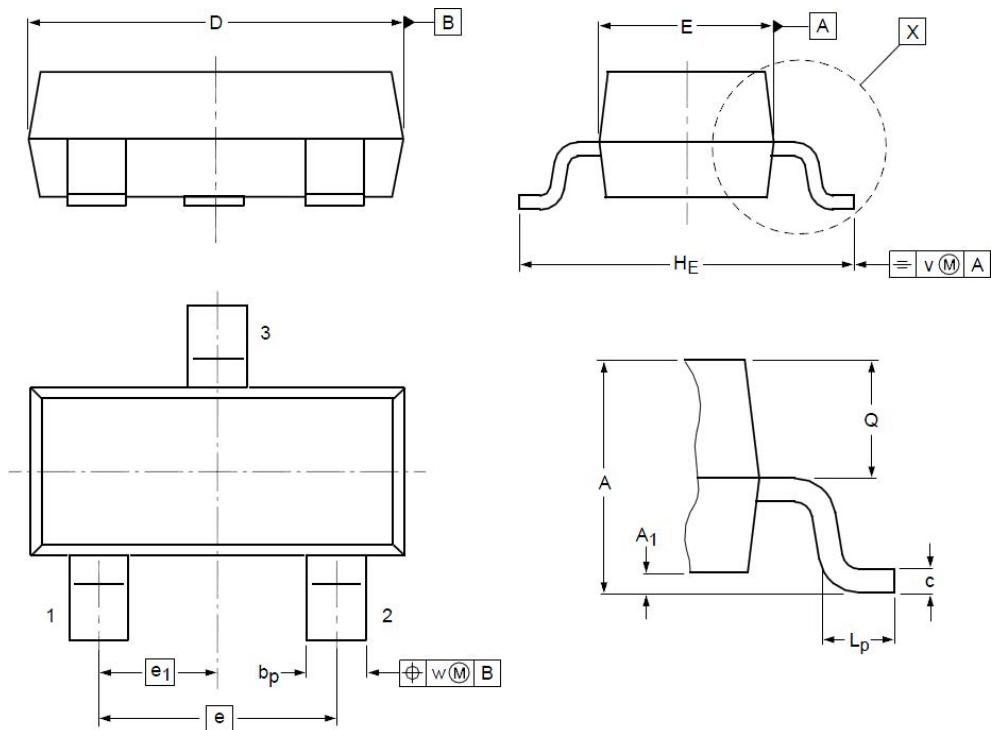
Drain Current



Thermal Transient Impedance



SOT23-3L Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.90	1.07	1.25	e₁	--	0.95	--
A₁	0.01	0.05	0.10	H_E	2.50	2.80	3.00
b_p	0.30	0.40	0.50	L_P	0.30	0.45	0.60
c	0.10	0.15	0.20	Q	0.23	0.28	0.33
D	2.70	2.90	3.10	V	--	0.20	--
E	1.40	1.55	1.75	W	--	0.20	--
e	--	1.90	--				